

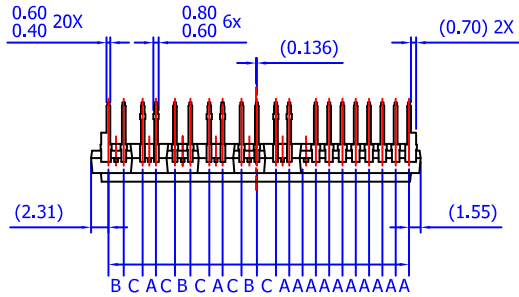
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



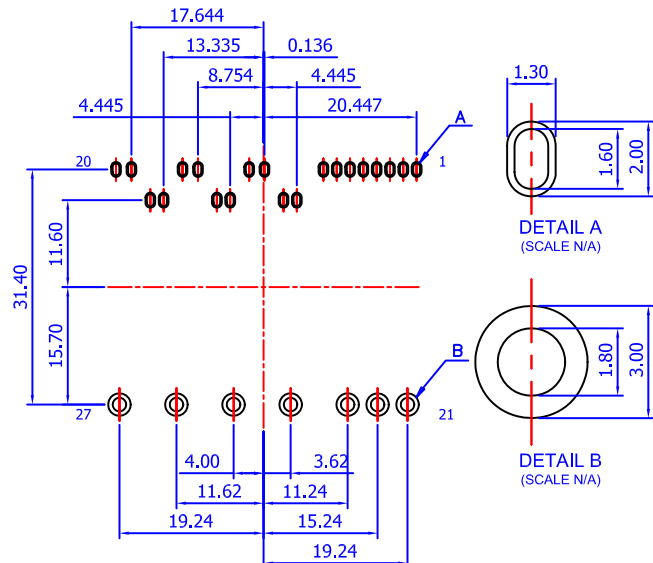
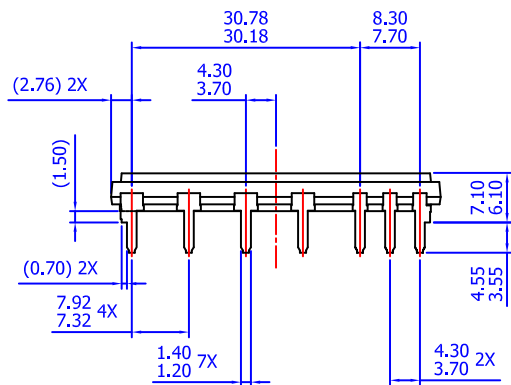
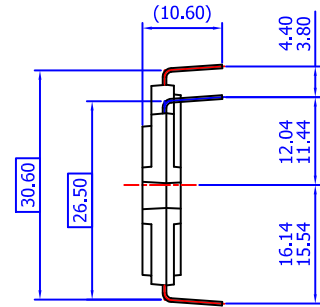
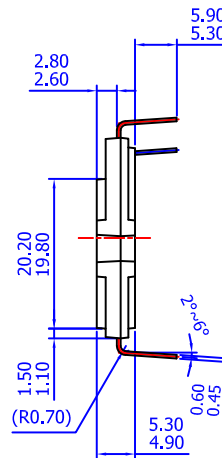
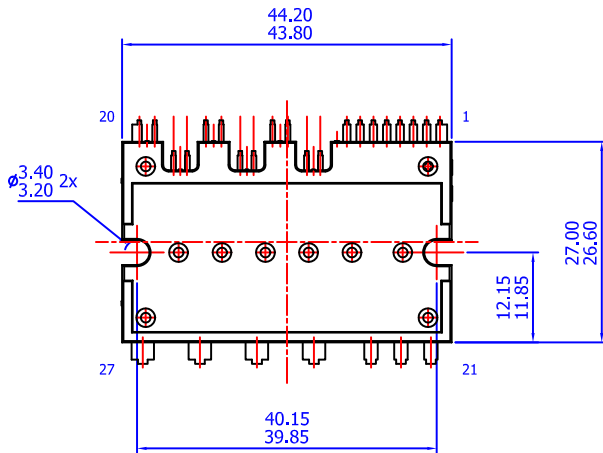
## SPMJB-027 / 27LD, PDD STD, SPM27-JB FULL PACK SHORT LEAD CASE MODDR ISSUE O

DATE 31 DEC 2016



LEAD PITCH (TOLERANCE : ±0.30)

- A : 1.778
- B : 2.050
- C : 2.531



### LAND PATTERN RECOMMENDATIONS

- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
  - B) ALL DIMENSIONS ARE IN MILLIMETERS
  - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
  - D) ( ) IS REFERENCE
  - E) [ ] IS ASS'Y QUALITY

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>SPMJB-027 / 27LD, PDD STD, SPM27-JB FULL PACK SHORT LEAD</b>	<b>PAGE 1 OF 2</b>

